XN01118 (XN1118)

Silicon PNP epitaxial planer transistor

For switching/digital circuits

Features

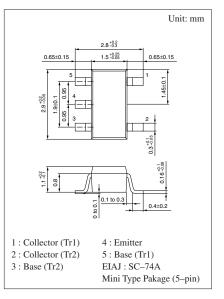
- Two elements incorporated into one package. (Emitter-coupled transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half.

Basic Part Number of Element

• UNR1118(UN1118) \times 2 elements

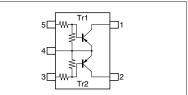
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Parameter		Symbol	Ratings	Unit			
Rating of element	Collector to base voltage	V _{CBO}	-50	V			
	Collector to emitter voltage	V _{CEO}	-50	V			
	Collector current	I _C	-100	mA			
Overall	Total power dissipation	P _T	300	mW			
	Junction temperature	Tj	150	°C			
	Storage temperature	T _{stg}	-55 to +150	°C			

Absolute Maximum Ratings (Ta=25°C)



Marking Symbol: OM

Internal Connection

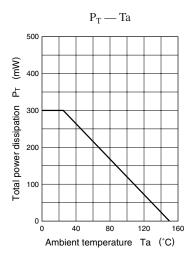


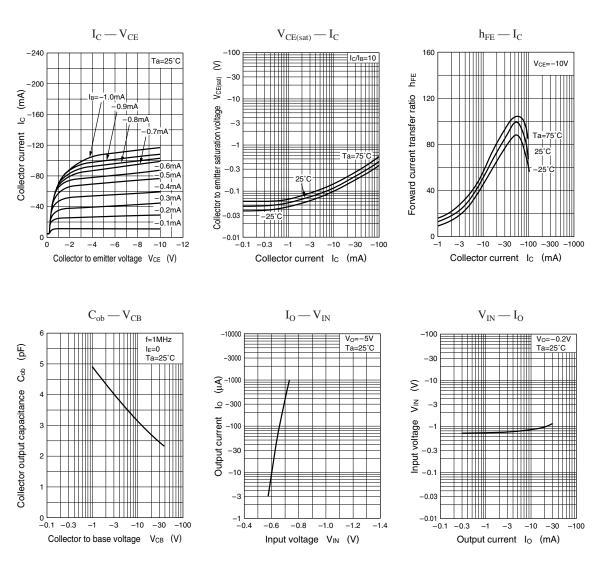
Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector to base voltage	V _{CBO}	$I_{\rm C} = -10 \mu A, \ I_{\rm E} = 0$	-50			V
Collector to emitter voltage	V _{CEO}	$I_{\rm C} = -2mA, I_{\rm B} = 0$	-50			V
Collector cutoff current	I _{CBO}	$V_{CB} = -50V, I_E = 0$			- 0.1	μΑ
	I _{CEO}	$V_{CE} = -50V, I_B = 0$			- 0.5	μΑ
Emitter cutoff current	I _{EBO}	$V_{EB} = -6V, I_C = 0$			- 2.0	mA
Forward current transfer ratio	h _{FE}	$V_{CE} = -10V, I_C = -5mA$	20			
Forward current transfer h_{FE} ratio	h _{FE} (small/large)*1	$V_{CE} = -10V, I_C = -5mA$	0.5	0.99		
Collector to emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -10 {\rm mA}, I_{\rm B} = -0.3 {\rm mA}$			- 0.25	V
Output voltage high level	V _{OH}	$V_{CC} = -5V, V_B = -0.5V, R_L = 1k\Omega$	-4.9			V
Output voltage low level	V _{OL}	$V_{CC} = -5V, V_B = -2.5V, R_L = 1k\Omega$			- 0.2	V
Transition frequency	f _T	$V_{CB} = -10V, I_E = 1mA, f = 200MHz$		80		MHz
Input resistance	R ₁		-30%	0.51	+30%	kΩ
Resistance ratio	R ₁ /R ₂		0.08	0.1	0.12	

*1 Ratio between 2 elements

Note.) The Part number in the Parenthesis shows conventional part number.





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